

(12) International Application Status Report

Received at International Bureau: 12 May 2020 (12.05.2020)

Information valid as of: 12 May 2020 (12.05.2020)

Report generated on: 24 February 2021 (24.02.2021)

(10) Publication number:

WO2020/226369

(43) Publication date:

12 November 2020 (12.11.2020)

(26) Publication language:

English (EN)

(21) Application Number:

PCT/KR2020/005798

(22) Filing Date:

29 April 2020 (29.04.2020)

(25) Filing language:

English (EN)

(31) Priority number(s):

10-2019-0052516 (KR)

(31) Priority date(s):

03 May 2019 (03.05.2019)

(31) Priority status:

Priority document received (in compliance with PCT Rule 17.1)

10-2019-0097215 (KR)

09 August 2019 (09.08.2019)

Priority document received (in compliance with PCT Rule 17.1)

10-2020-0046933 (KR)

17 April 2020 (17.04.2020)

Priority document received (in compliance with PCT Rule 17.1)

(51) International Patent Classification:

H01L 27/15 (2006.01); **H01L 33/02** (2010.01); **H01L 33/62** (2010.01); **H01L 33/38** (2010.01)

(71) Applicant(s):

SAMSUNG ELECTRONICS CO., LTD. [KR/KR]; 129, Samsung-ro, Yeongtong-gu Suwon-si Gyeonggi-do 16677 (KR) (*for all designated states*)

(72) Inventor(s):

LEE, Chang Joon; 129, Samsung-ro, Yeongtong-gu Suwon-si Gyeonggi-do 16677 (KR)
SON, Seong Ho; 129, Samsung-ro, Yeongtong-gu Suwon-si Gyeonggi-do 16677 (KR)
LEE, Jong Sung; 129, Samsung-ro, Yeongtong-gu Suwon-si Gyeonggi-do 16677 (KR)
JUNG, Young Ki; 129, Samsung-ro, Yeongtong-gu Suwon-si Gyeonggi-do 16677 (KR)

(74) Agent(s):

SELIM INTELLECTUAL PROPERTY LAW FIRM; 10F and 11F, Taewoo Bldg., 285, Gangnamdaero Seocho-gu Seoul 06729 (KR)

(54) Title (EN): LIGHT EMITTING DIODE MODULE

(54) Title (FR): MODULE DE DIODE ÉLECTROLUMINESCENTE

(57) Abstract:

(EN): A light emitting diode (LED) module includes an integrated substrate, the integrated substrate including a plurality of LEDs; a glass substrate; and a signal wiring layer provided on the glass substrate. The signal wiring layer includes a plurality of signal electrodes configured to supply a data signal to the plurality of LEDs. The LED module further includes a conductive pattern provided on at least one surface of the integrated substrate, and connected to a ground.

(FR): Un module de diode électroluminescente (DEL) comprend un substrat intégré, le substrat intégré comprenant une pluralité de DEL ; un substrat de verre ; et une couche de câblage de signal disposée sur le substrat de verre. La couche de câblage de signal comprend une pluralité d'électrodes de signal conçues pour fournir un signal de données à la pluralité de DEL. Le module de DEL comprend en outre un motif conducteur disposé sur au moins une surface du substrat intégré, et connecté à une masse.

International search report:

Received at International Bureau: 04 September 2020 (04.09.2020) [KR]

International Report on Patentability (IPRP) Chapter II of the PCT:

Not available

(81) Designated States:

AE, AG, AL, AM, AO, AT, AU, AZ, BA, BB, BG, BH, BN, BR, BW, BY, BZ, CA, CH, CL, CN, CO, CR, CU, CZ, DE, DJ, DK, DM, DO, DZ, EC, EE, EG, ES, FI, GB, GD, GE, GH, GM, GT, HN, HR, HU, ID, IL, IN, IR, IS, JO, JP, KE, KG, KH, KN, KP, KW, KZ, LA, LC, LK, LR, LS, LU, LY, MA, MD, ME, MG, MK, MN, MW, MX, MY, MZ, NA, NG, NI, NO, NZ, OM, PA, PE, PG, PH, PL, PT, QA, RO, RS, RU, RW, SA, SC, SD, SE, SG, SK, SL, ST, SV, SY, TH, TJ, TM, TN, TR, TT, TZ, UA, UG, US, UZ, VC, VN, WS, ZA, ZM, ZW

European Patent Office (EPO) : AL, AT, BE, BG, CH, CY, CZ, DE, DK, EE, ES, FI, FR, GB, GR, HR, HU, IE, IS, IT, LT, LU, LV, MC, MK, MT, NL, NO, PL, PT, RO, RS, SE, SI, SK, SM, TR

African Intellectual Property Organization (OAPI) : BF, BJ, CF, CG, CI, CM, GA, GN, GQ, GW, KM, ML, MR, NE, SN, TD, TG

African Regional Intellectual Property Organization (ARIPO) : BW, GH, GM, KE, LR, LS, MW, MZ, NA, RW, SD, SL, ST, SZ, TZ, UG, ZM, ZW

Eurasian Patent Organization (EAPO) : AM, AZ, BY, KG, KZ, RU, TJ, TM